

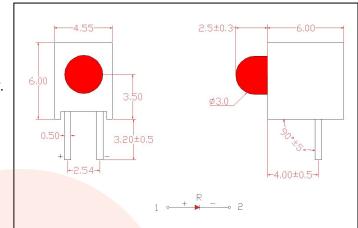
Features:

- 1. Chip material:AlGaAs(Red)
- 2. Emitted color: Red
- 3. Lens Appearance : Red Diffused
- 4. Designed for ease in circuit board assembly.
- 5. Black case enhance contrast ratio.
- 6. Solid state light source.
- 7. Reliable and rugged.
- 8. 3mm diameter package.
- This product don't contained restriction substance, compliance ROHS standard.

Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Package dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

| Parameter | Symbol | Red | Unit |
|------------------------|-----------------|-----------------------|------|
| Power Dissipation | Pd | 75 | mW |
| Forward Current | I _F | 30 | mA |
| Peak Forward Current*1 | I _{FP} | 150 | mA |
| Reverse Voltage | V _R | 5 | V |
| Operating Temperature | Topr | -30℃~80℃ | |
| Storage Temperature | Tstg | -40℃~85℃ | |
| Soldering Temperature | Tsol | 260°C (for 5 seconds) | |

^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

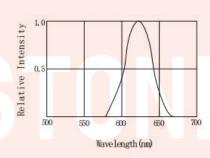


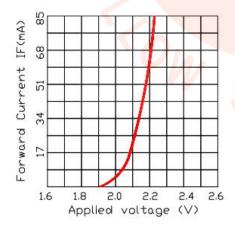
■ Electrical and optical characteristics(Ta=25°C)

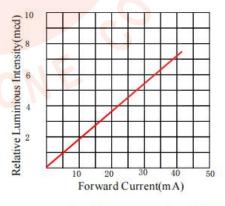
| Parameter | Symbol | Condition | Color | Min. | Тур. | Max. | Unit |
|--------------------------|-------------------|----------------------|-------|------|------|------|------|
| Forward Voltage | V _F | I _F =20mA | Red | 1.8 | | 2.4 | V |
| Luminous Intensity | lv | I _F =20mA | Red | 1 | | 10 | mcd |
| Reverse Current | I _R | V _R =1V | Red | ı | 1 | 2 | μΑ |
| Dominant Wave Length | λd | I _F =20mA | Red | 630 | - | 650 | nm |
| Spectral Line Half-width | Δλ | I _F =20mA | Red | - | - | - | nm |
| Viewing Angle | 2θ _{1/2} | I _F =20mA | Red | - | 50 | - | deg |

■ Typical Electro-Optical Characteristics Curves

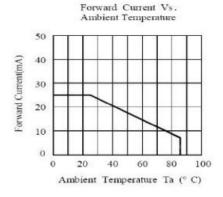
Red

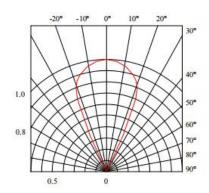






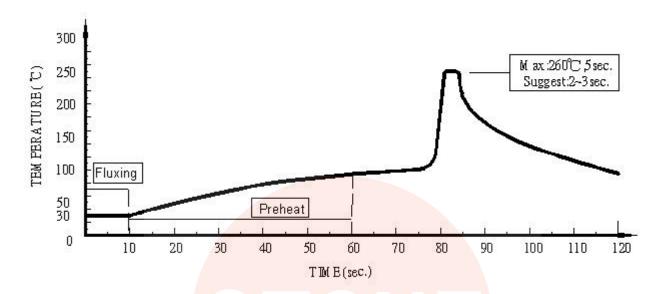
Forward Currend Vs Relative luminious Intensity







Dip Soldering



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A: Max: 350° C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350 ℃ Within 2 sec. One time only